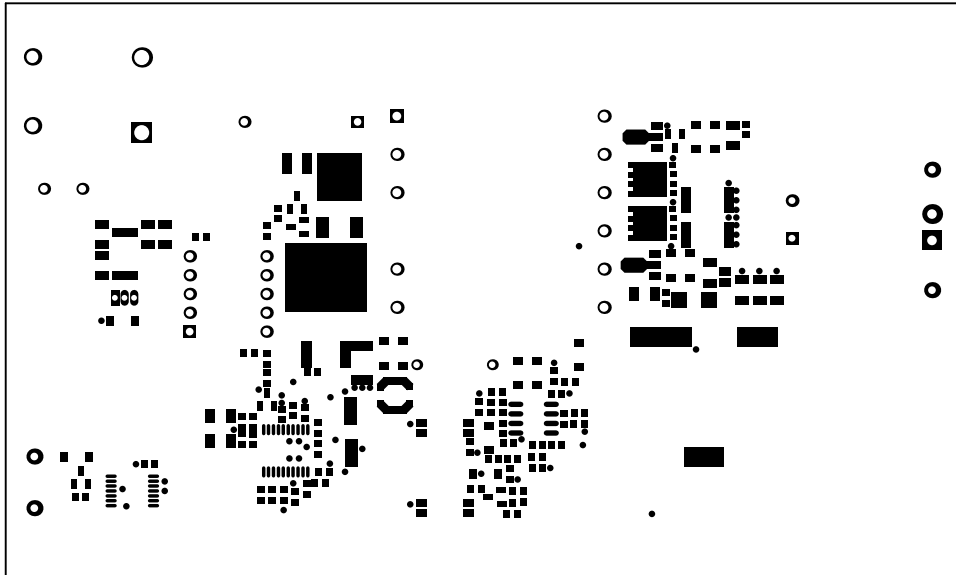
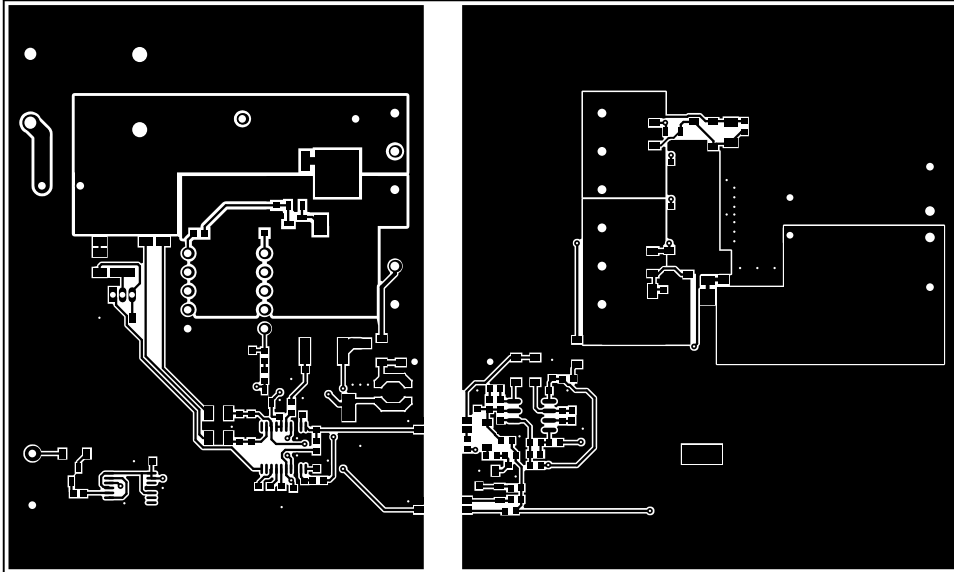


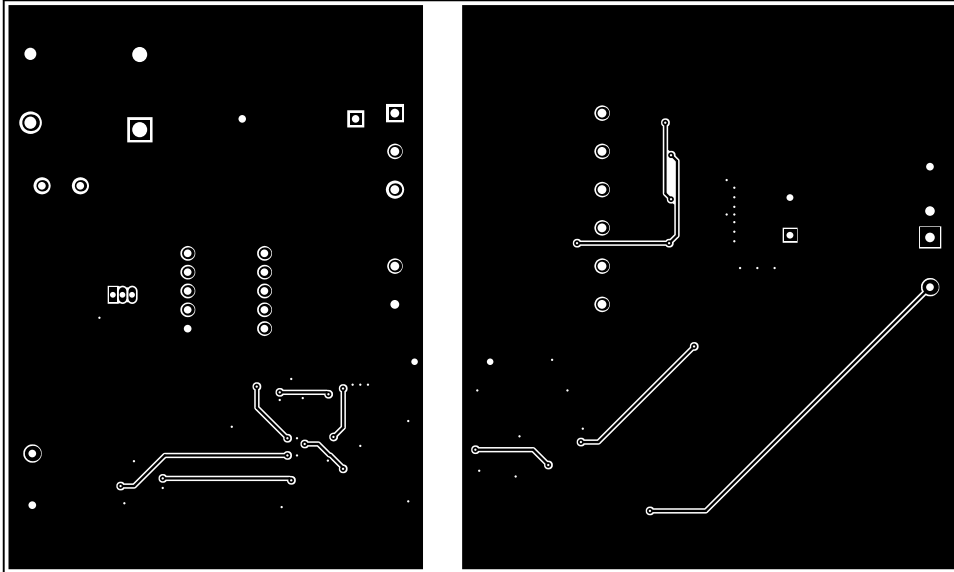
|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay         |                                   |                   |                                |
| PLOT NAME = Top Overlay          | GENERATED : 1/22/2014 10:55:55 AM | TEXAS INSTRUMENTS |                                |



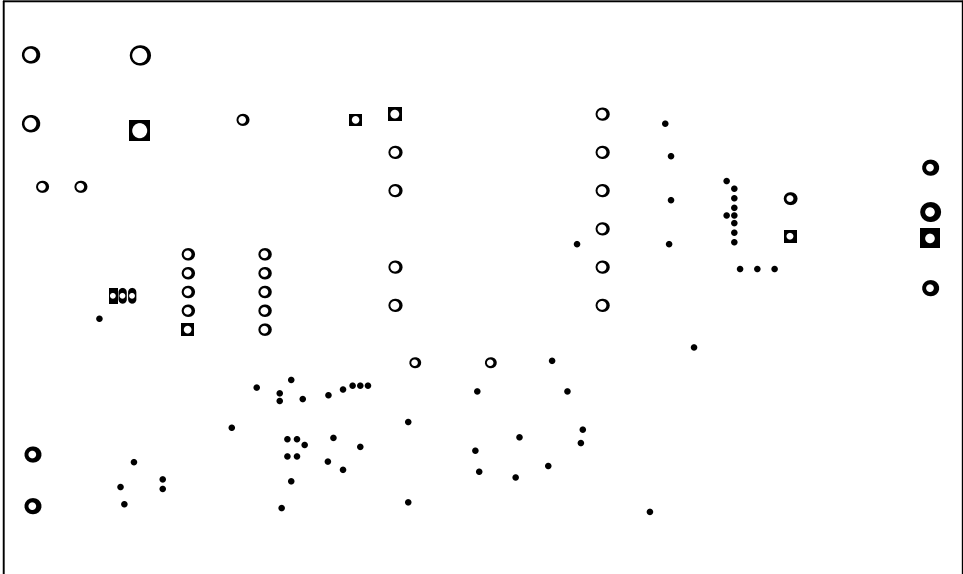
|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder          |                                   |                   |                                |
| PLOT NAME = Top Solder Mask      | GENERATED : 1/22/2014 10:55:56 AM | TEXAS INSTRUMENTS |                                |



|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer           |                                   |                   |                                |
| PLOT NAME = Top Layer            | GENERATED : 1/22/2014 10:55:57 AM | TEXAS INSTRUMENTS |                                |



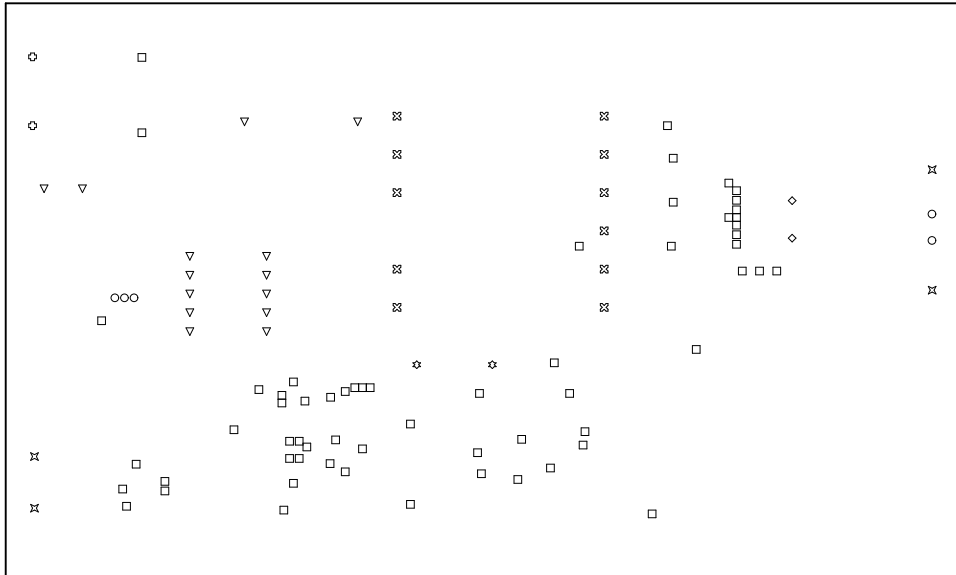
|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer        |                                   |                   |                                |
| PLOT NAME = Bottom Layer         | GENERATED : 1/22/2014 10:55:58 AM | TEXAS INSTRUMENTS |                                |



|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder       |                                   |                   |                                |
| PLOT NAME = Bottom Solder Mask   | GENERATED : 1/22/2014 10:55:59 AM | TEXAS INSTRUMENTS |                                |



|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay      |                                   |                   |                                |
| PLOT NAME = Bottom Overlay       | GENERATED : 1/22/2014 10:55:59 AM | TEXAS INSTRUMENTS |                                |



| Symbol    | Hit Count | Tool Size          | Plated | Hole Type |
|-----------|-----------|--------------------|--------|-----------|
| □         | 59        | 12mil (0.305mm)    | PTH    | Round     |
| ○         | 3         | 29.528mil (0.75mm) | PTH    | Round     |
| ⊗         | 2         | 33.465mil (0.85mm) | PTH    | Round     |
| ◇         | 2         | 35.433mil (0.9mm)  | PTH    | Round     |
| ▽         | 14        | 39.37mil (1mm)     | PTH    | Round     |
| ⊗         | 4         | 40mil (1.016mm)    | PTH    | Round     |
| ⊗         | 11        | 45.3mil (1.151mm)  | PTH    | Round     |
| ○         | 2         | 50mil (1.27mm)     | PTH    | Round     |
| ⊗         | 2         | 63mil (1.6mm)      | PTH    | Round     |
| □         | 2         | 78.74mil (2mm)     | PTH    | Round     |
| 101 Total |           |                    |        |           |

Drill Table

|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing       |                                   |                   |                                |
| PLOT NAME = Drill Drawing        | GENERATED : 1/22/2014 10:56:00 AM | TEXAS INSTRUMENTS |                                |



←1000 (mil)→

|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP6961                  | REV: E            | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions |                                   |                   |                                |
| PLOT NAME = Board Dimensions     | GENERATED : 1/22/2014 10:56:01 AM | TEXAS INSTRUMENTS |                                |



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